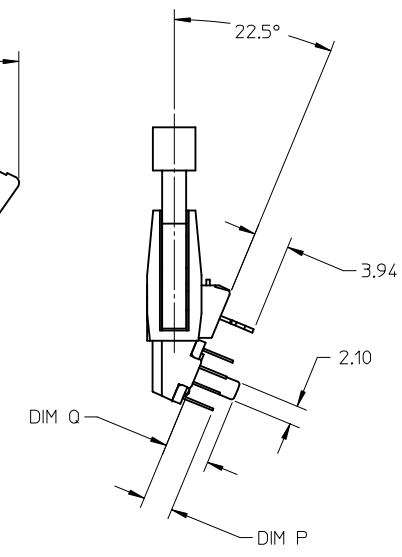
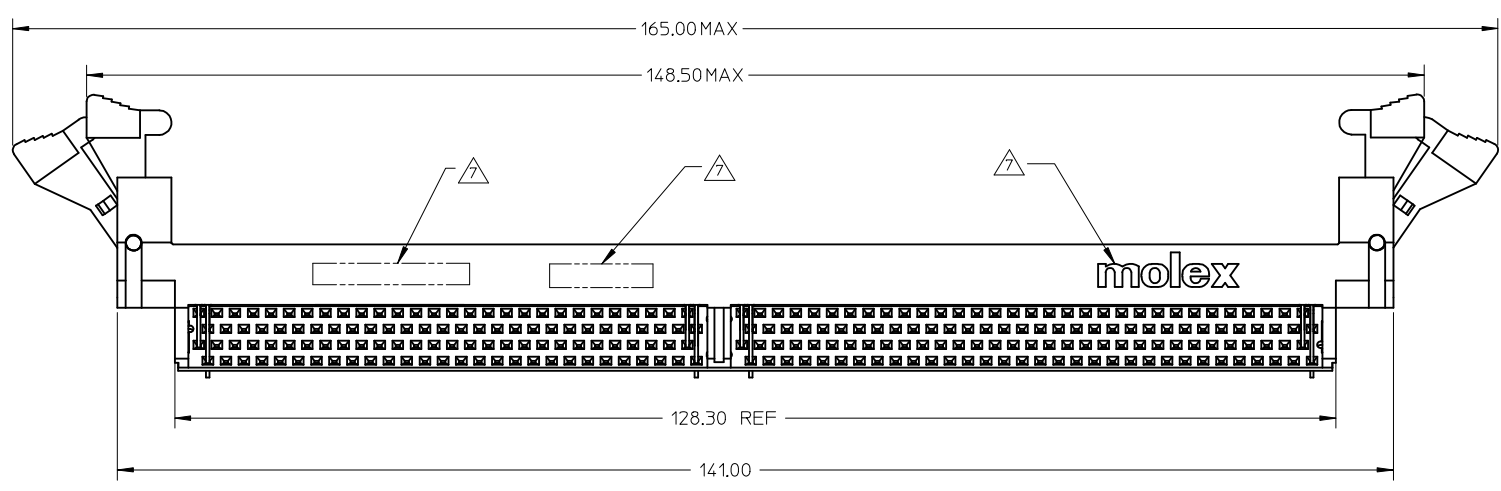
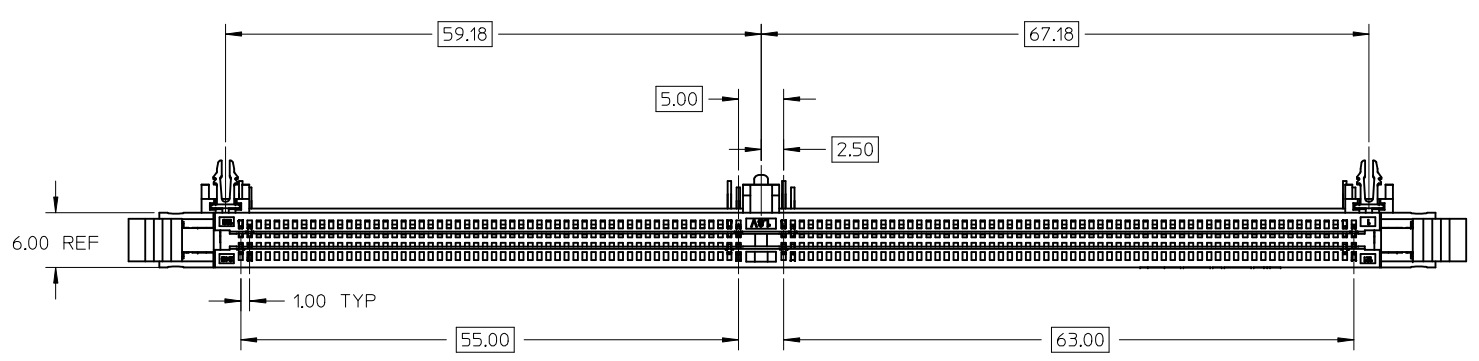


10 9 8 7 6 5 4 3 2 1



- NOTES :
- MATERIALS : HOUSING, BASEPLATE AND LATCH.
- HIGH TEMP THERMOPLASTIC, UL94-0.
TERMINALS & FORKLOCK - COPPER ALLOY.
 - PLATING : CONTACT AREA - SEE TABLE IN SHEET 5.
SOLDERTAIL - SEE TABLE IN SHEET 5.
 - CARD SLOT ACCEPTS 1.27+/-0.10MM MODULE THICKNESS (MEASURED OVER PC PADS).
 - REFER TO PRODUCT SPECIFICATION , PS-87916-001 FOR PERFORMANCE SPECIFICATION.
 - RECOMMENDED MODULE CARD LAYOUT SHALL BE AS PER JEDEC MO-237.
 - PRODUCT SHALL BE PACKED IN TRAY.
- △ MOLEX LOGO, DATE CODE & PART NUMBER INDICATED ON HOUSING.

ADDED OPTION
EC NO: S2008-0329
2007/10/24
DRW:NCCTEH
CHKD:TYANG01
2007/10/24
APPR:SHLENI
2007/10/25

QUALITY SYMBOLS
▽=0
◻=0

GENERAL TOLERANCES (UNLESS SPECIFIED)	
	mm INCH
4 PLACES	± --- ± ---
3 PLACES	± --- ± ---
2 PLACES	± 0.25 ± ---
1 PLACE	± --- ± ---
ANGULAR ± 5 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	
MM ONLY	
DRAWN BY	DATE
JTAN	2004/05/11
CHECKED BY	DATE
MLONG	2004/06/11
APPROVED BY	DATE
GGLEE	2004/06/11
MATERIAL NO.	
SEE TABLE	
SIZE	A3

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
NTS	METRIC	☉
TITLE		
DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG		
MOLEX MOLEX INCORPORATED		
DOCUMENT NO.	SHEET NO.	
SD-87916-001	1 OF 5	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

F

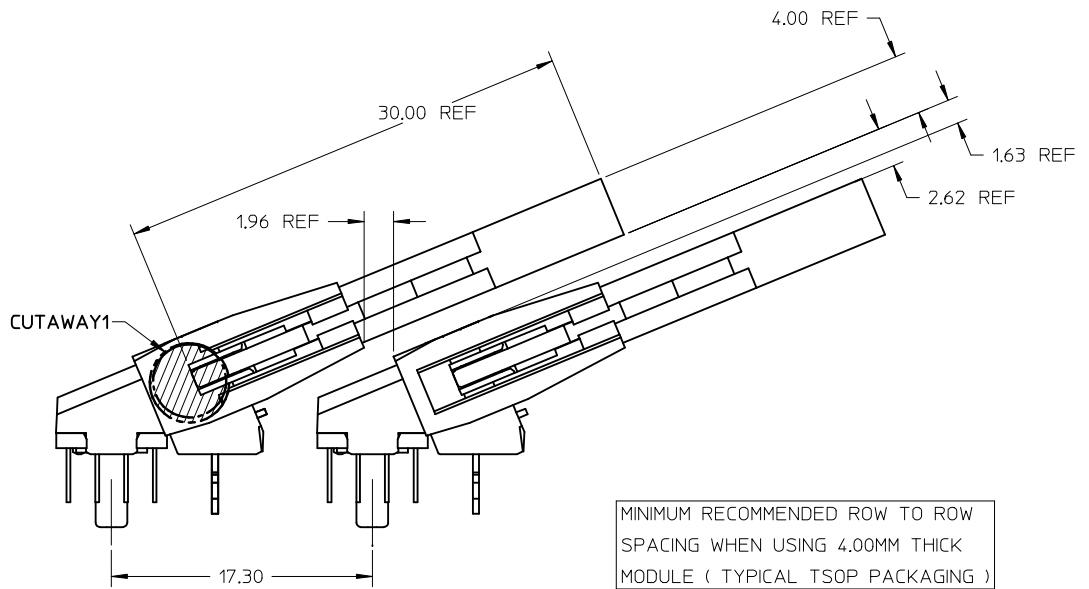
E

D

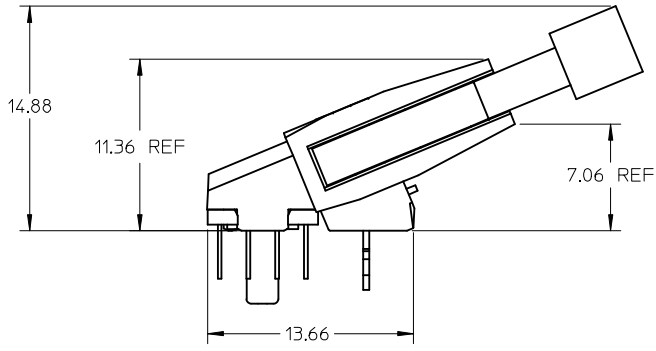
C

B

A

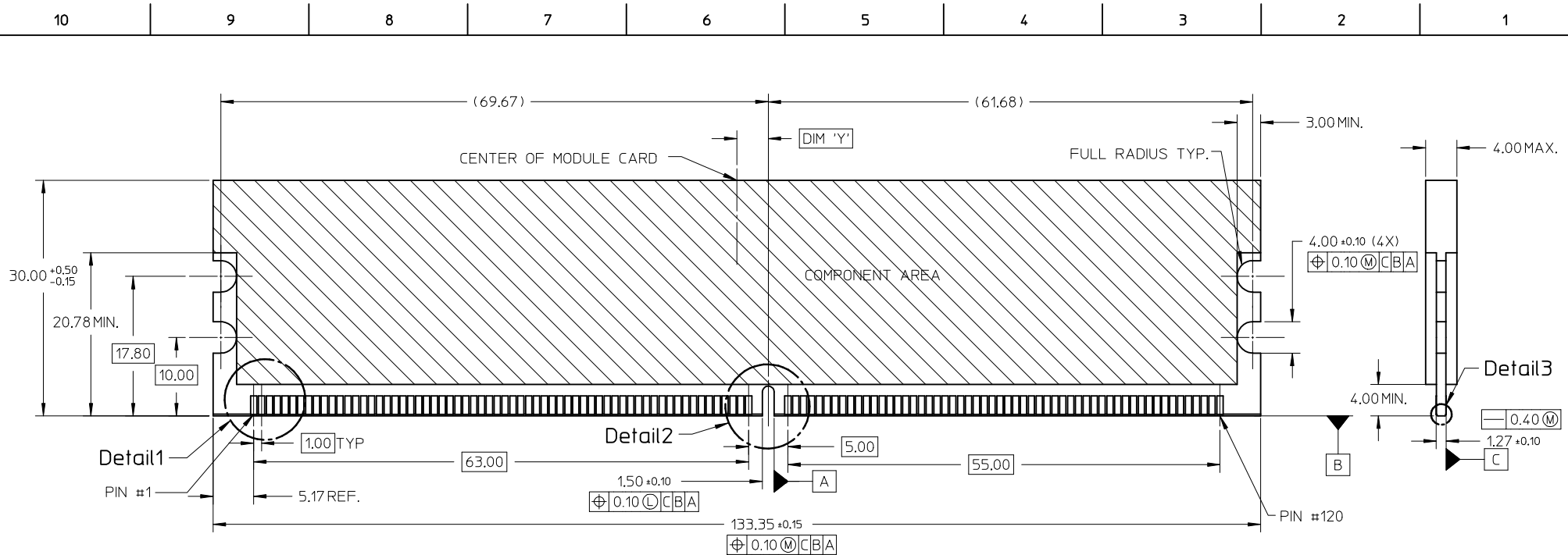


MINIMUM RECOMMENDED ROW TO ROW SPACING WHEN USING 4.00MM THICK MODULE (TYPICAL TSOP PACKAGING)

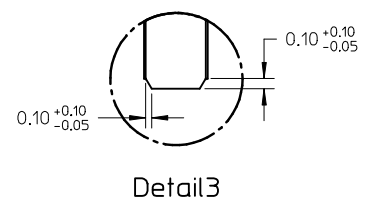
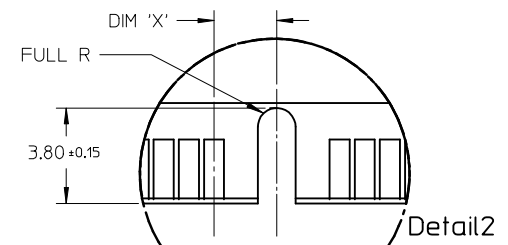
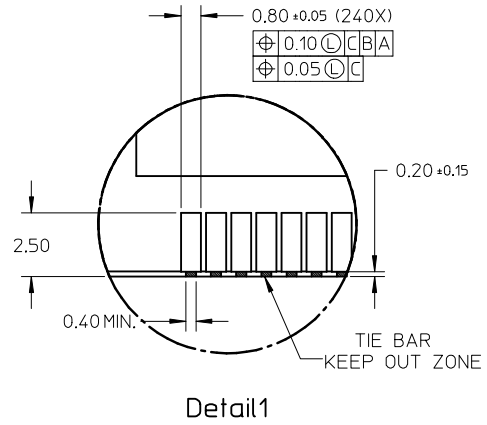


ADDED OPTION EC NO: S2008-0329 DRW/CCTH CH/KD: YIANG01 APPR: SHLENI 2007/10/24 2007/10/24 2007/10/25	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
					DRAWN BY JTAN	DATE 2004/05/11	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG	
					CHECKED BY MLONG	DATE 2004/06/11	MOLEX INCORPORATED	
					APPROVED BY GGLEE	DATE 2004/06/11	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-87916-001
A1	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

9 8 7 6 5 4 3 2 1

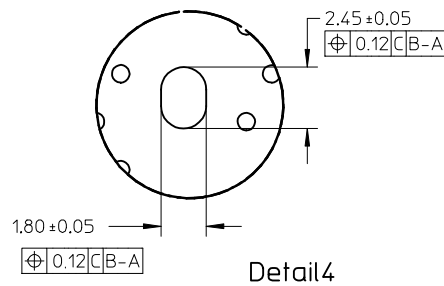
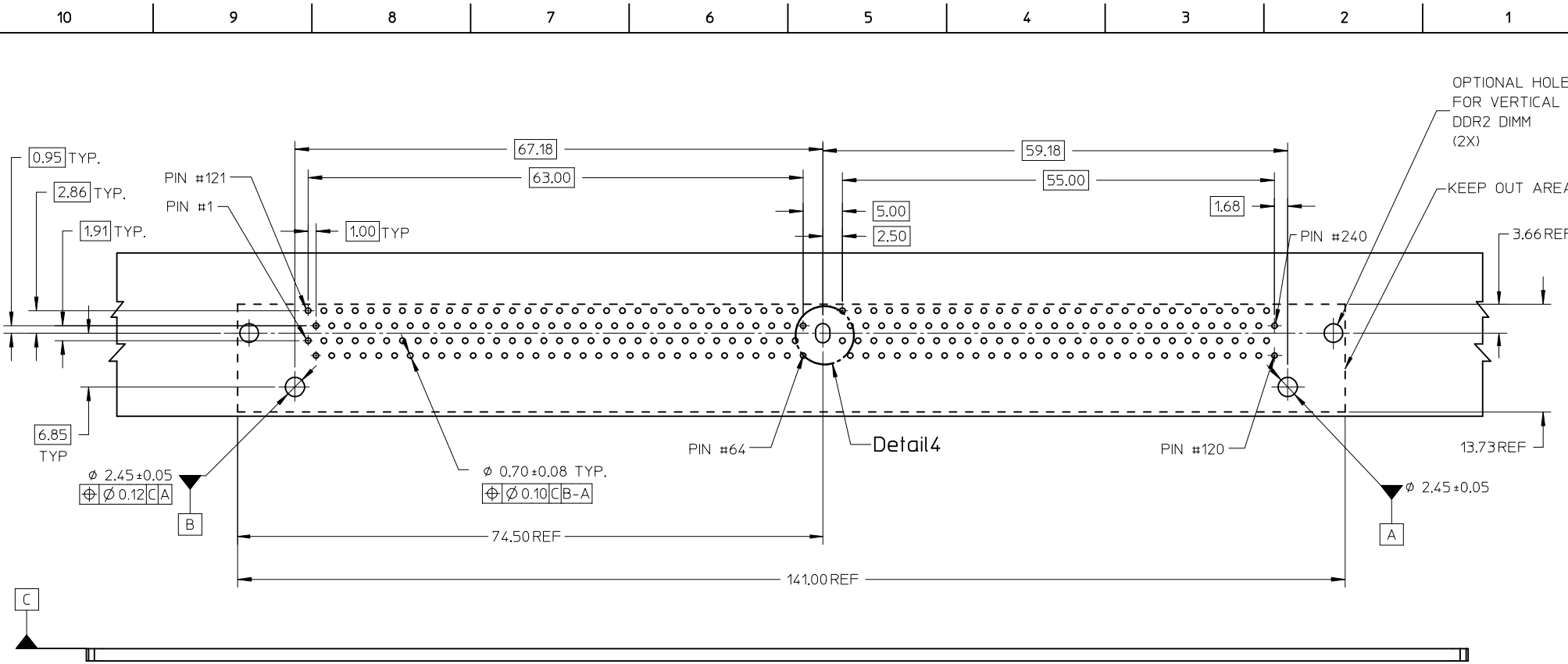


RECOMMENDED MODULE LAYOUT



KEY LOCATION	VOLTAGE	DIM 'X'	DIM 'Y'
CENTER	1.8V	2.50	4.00

ADDED OPTION EC NO: S2008-0329 DRW: CTEH CHKD: YIANG01 APPR: SHLENI	2007/10/24 2007/10/24 2007/10/25	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 C=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
					mm INCH	DRAWN BY JTAN	DATE 2004/05/11	TITLE DDR2 DIMM, 100MM PITCH 240 CKTS, 22.5 DEG			
					4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± ---	CHECKED BY MLONG	DATE 2004/06/11	MOLEX INCORPORATED			
					ANGULAR ± 5 °	APPROVED BY GGLEE	DATE 2004/06/11	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-87916-001	SHEET NO. 3 OF 5	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



ADDED OPTION EC NO: S2008-0329 DRWN: CCTH CH'KD: YTYANG01 APPR: SHLENI 2007/10/24 2007/10/24 2007/10/25	QUALITY SYMBOLS 	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± ---	mm INCH	DRAWN BY: JTAN CHECKED BY: MLONG APPROVED BY: GGLEE	DATE: 2004/05/11 DATE: 2004/06/11 DATE: 2004/06/11	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG			
		ANGULAR ± 5 °		MATERIAL NO.	MOLEX INCORPORATED				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE	DOCUMENT NO.	SD-87916-001			
A1	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SIZE A3	SHEET NO. 4 OF 5				

PART NO.	VOLTAGE KEY	DIM 'P'	DIM 'Q'	RECOMMENDED PCB THICKNESS	CONTACT AREA PLATING	SOLDERTAIL PLATING
87916-0001	1.8V	2.79	3.18	1.57	0.76uM/ 30u" GOLD OVER 1.27uM/ 50u" MIN NICKEL	2.54uM/ 100u" MIN. TIN OVER 1.27uM/ 50u" MIN NICKEL
87916-0011		3.18	4.83	2.36		
87916-0111		4.00		3.20		

ADDED OPTION EC NO: S2008-0329 2007/10/24 DRW:CCTEH 2007/10/24 CHKD:TYANG01 2007/10/24 APPR:SHLENI 2007/10/25	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 □=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
			4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± ---	mm INCH ± --- ± --- ± 0.25 ± --- ± --- ± ---	DRAWN BY JTAN	DATE 2004/05/11	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 22.5 DEG			
			ANGULAR ± 5 °	CHECKED BY MLONG	DATE 2004/06/11	MOLEX INCORPORATED				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE	APPROVED BY GGLEE	DATE 2004/06/11	DOCUMENT NO. SD-87916-001	SHEET NO. 5 OF 5			